

Drafts

 Pending

- L1: (1) ("5814557"). PN.
- L2: (1) ("5256274"). PN.
- L3: (1583972) heat or heats or heated or heating
- L4: (151341) anneal or anneals or annealed or annealing
- L5: (0) 12 and 14
- L6: (1) 12 and 13
- L7: (56603) electroplatS or electrodepositS
- L8: (13537) (electrolytS or electrochemS) near2 depositS
- L9: (15970) (electrolytS or electrochemS) near2 depositS
- L10: (73627) 17 or 18 or 19
- L11: (486440) copper or Cu
- L12: (26527) 110 same 111
- L13: (3886) 112 and 14
- L14: (210263) wafer or wafers
- L15: (1928) 113 and 114
- L16: (975) 112 same 14
- L17: (544) 116 and 114

 Failed

- Saved
- Favorites
- Tagged (3)
- UDC
- Queue
- Trash

<input type="checkbox"/> Drafts	<input type="checkbox"/> List	<input type="checkbox"/> Browse	<input type="checkbox"/> Details	<input type="checkbox"/> Clear
<input checked="" type="checkbox"/> Active	<input type="checkbox"/> US PGPUB: USPAI	<input type="checkbox"/> Details	<input type="checkbox"/> Print	<input type="checkbox"/> Home
<input checked="" type="checkbox"/> Pending	<input type="checkbox"/> Default operator: ADU	<input type="checkbox"/> F	<input type="checkbox"/> Home at hot terms index	
<input type="checkbox"/> L1: (1) ("5814557"). PN. <input type="checkbox"/> L2: (1) ("5256274"). PN. <input type="checkbox"/> L3: (1583972) heat or heats or heated or heating <input type="checkbox"/> L4: (151341) anneal or anneals or annealed or annealing <input type="checkbox"/> L5: (0) 12 and 14 <input type="checkbox"/> L6: (1) 12 and 13 <input type="checkbox"/> L7: (56603) electroplatS or electrodepositS <input type="checkbox"/> L8: (13537) (electrolytS or electrochemS) near2 depositS <input type="checkbox"/> L9: (15970) (electrolytS or electrochemS) near2 depositS <input type="checkbox"/> L10: (73627) 17 or 18 or 19 <input type="checkbox"/> L11: (486440) copper or Cu <input type="checkbox"/> L12: (26527) 110 same 111 <input type="checkbox"/> L13: (3886) 112 and 14 <input type="checkbox"/> L14: (210263) wafer or wafers <input type="checkbox"/> L15: (1928) 113 and 114 <input type="checkbox"/> L16: (975) 112 same 14 <input type="checkbox"/> L17: (544) 116 and 114				

Document ID	Issue ID	Issue Date	Pages	Title	Current OR	Current XRef	Inventor	U	S	C	P	1	3	4	5	6
1	US 20060003579	20060105	15	Interconnects with direct metalization and conductive polymer	438/639		Sir; Jiuu Hann	<input checked="" type="checkbox"/>	<input type="checkbox"/>							
2	US 20060003546	20060105		Highly compliant plate for wafer bonding	438/455	438/457	Kobrinsky; Mauro J. et al.	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	
3	US 20060003547	20060105		Highly compliant plate for wafer bonding	438/455	438/457	Kobrinsky; Mauro J. et al.	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	
4	US 20060003486	20060105		Plasma treatment method for electron migration reduction	438/76		Iai; Jane-Bai et al.	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	
5	US 20050287785	20051229		Method of stacking wafers with anisotropic conductive adhesive	438/613	257/734	Lee, Kevin J.	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	
6	US 20050282371	20051222		Sequential station tool for wet processing of semiconductor wafers	438/597		Patton, Evan E. et al.	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	
7	US 20050260411	20051124		Diamond-like carbon films with low dielectric constant and high mechanical	428/408	427/249.7;	Ravi, Kramadhati V.	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	
8	US 20050245082	20051103		Apparatus and method for electrochemically depositing metal on a metal layer	438/687	427/569	Chen, Linlin et al.	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	
9	US 20050245072	20051103		Method and apparatus for fabricating metal layer	438/628	438/643; 438/644	Lee, Hsien-Ming et al.	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	
10	US 20050239276	20051027		Process of forming a composite diffusion barrier in copper/organic low-k	438/618		Li, Chacyong et al.	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	
11	US 20050233591	20051020		Techniques promoting adhesion of porous low K film to underlying barrier layer	438/706	216/34; 216/67;	Schmitt, Francimar et al.	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	
12	US 20050230834	20051020		Multi-stage curing of low K nano-porous films	257/758	257/762; 438/781;	Schmitt, Francimar et al.	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	